IPC ASSOCIATION ELECTRONIC	© Copyri	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				nder both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x				lard	Form Type * Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information							
Supplie	r Information							·								
Company name*				Company unique ID			J	Unique ID Authority					Response Date*			
nsemi													2024-05-15			
Contact Name				Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-l	Env-Stewards			Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*				Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-Env-Stewards				Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
	Requester Item Num	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Dat	e V	ersion 1	Manufacturing Site		W	eight*	UOM	Unit Type
		NCV8452STT1G 40V		40V Single Channel HS Driver		2024-05-15					10)9.99	mg	Each		
Ianufa	acturing Process								•	,					·	
	8			,		-STD-020 MSL	Rating			_ ·	ture Max Time at Peak Tem		Temperatu	re Numb	per of Reflow Cyc	les
Matte Tin (Sn) - annealed			C	CU Alloy 1				260		C	30		second	s 3		
omments																
<u>vel 1 - m</u>	naximum time at peak	temperature du	ıring sold	dering is 10-3	0 seconds											
or more	information regardin	g material comp	osition p	lease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to suc											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.3	mg	Supplier	Silicon (Si)	7440-21-3		3.3	mg
Die Attach Solder	2.37	mg	Supplier	Silver (Ag)	7440-22-4		0.0592	mg
			A	Lead (Pb)	7439-92-1	7a	2.2633	mg
			Supplier	Tin (Sn)	7440-31-5		0.0474	mg
Lead Frame	37.17		Supplier	Silver (Ag)	7440-22-4		0.4832	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0372	mg
			Supplier	Iron (Fe)	7439-89-6		0.8921	mg
			Supplier	Copper (Cu)	7440-50-8		35.7575	mg
Mold Compound-Black	59.7			Epoxy resin	proprietary data		4.4775	mg
			Supplier	Phenolic Resin	Proprietary Data		1.4925	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		4.4775	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2985	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		48.954	mg
Plating	7.44	mg	Supplier	Tin (Sn)	7440-31-5		7.44	mg
Wire Bond - Au	0.01	mg	Supplier	Gold (Au)	7440-57-5		0.01	mg